

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 08-032240

(43)Date of publication of application : 02.02.1996

(51)Int.Cl. H05K 3/46
H01L 23/12
H05K 1/02
H05K 3/38
H05K 3/42

(21)Application number : 06-159059

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(22)Date of filing : 12.07.1994

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(30)Priority

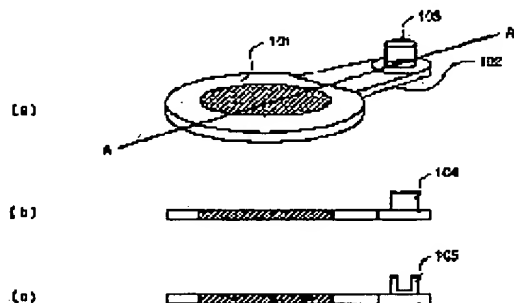
Priority number : 06 98975 Priority date : 13.05.1994 Priority country : JP

(54) MULTILAYER WIRING BOARD, PRODUCTION OF THE BOARD AND SEMICONDUCTOR DEVICE USING THE BOARD

(57)Abstract:

PURPOSE: To obtain a structure for forming high density wiring by extending a land present on the circumferential fringe of a filled plated through hole and forming a via for connecting with an upper or lower wiring layer in the surface at the extended land part.

CONSTITUTION: A land 101 formed on the circumferential fringe of a filled plated through hole in a double side printed wiring board is partially extended 102. A via 103 for connection with the wiring layer in a sequentially laminated thin film layer on the outside is formed at the forward end of the extended land part 102. A stud via 104 or a conformal via 105 may be employed and the stud via 104 is preferably employed because a finer via, having not a truncated conical profile but a columnar profile, can be formed.



LEGAL STATUS

[Date of request for examination] 13.09.1999

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's

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